## Product End-of-Life Disassembly Instructions

### Purpose:
The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Acbel STD</td>
<td>3</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink,</td>
<td>Include the cartridges, print heads, tubes, vent</td>
<td></td>
</tr>
</tbody>
</table>
including liquids, semi-liquids (gel/paste) and toner chambers, and service stations.

Components and waste containing asbestos

Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

**2.0 Tools Required**

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>T-15</td>
</tr>
<tr>
<td>Micro shear</td>
<td>170II</td>
</tr>
<tr>
<td>Screwdriver</td>
<td>PH1</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

**3.0 Product Disassembly Process**

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Loose the screw and remove access panel.(see Figure 1 below)
2. Rotate the driver cage from the hook on slide rail.(see Figure 2-6 below)
3. Disconnect FIO cables from the MB.(see Figure 7-9 below)
4. Disconnect HDD SATA cables from the MB.(see Figure 10 below)
5. Disconnect other PSU cables from the MB.(see Figure 11 below)
6. Remove ODD SATA/power cable.(see Figure 12-13 below)
7. Remove the memory from MB.(see Figure 14 below)
8. Remove ODD from chassis.(see Figure 15-16 below)
9. Remove FIO/PSU/Speaker/SATA power/system fan cables from the MB.(see Figure 17-24 below)
10. Remove system fan from chassis.(see Figure 25 below)
11. Remove the heatsink from MB.(see Figure 26-27 below)
12. Separate the fan from CPU heatsink.(see Figure 28-29 below)
13. Remove the CPU from the MB.(see Figure 30-31 below)
14. Remove the battery from the MB.(see Figure 32 below)
15. Remove M/B from chassis.(see Figure 33-34 below)
16. Remove front panel from chassis.(see Figure 35 below)
17. Remove FIO/Speaker from chassis.(see Figure 36-38 below)
18. Remove HDD from HDD cage.(see Figure 39 below)
19. Remove PSU cover.(see Figure 40-46 below)
20. Disconnect all the cables and remove the Electrolytic Capacitors.(see Figure 47-52 below)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1  Press access panel latch remove access panel

Figure 2  Remove the cable from the hook

Figure 3  Press the latch on ODD cage

Figure 4  Disconnect HDD Power cable from HDD

Figure 5  Disconnect SATA cable from HDD

Figure 6  Remove HDD cage

PSG instructions for this template are available at EL-MF877-01
Figure 7 Disconnect FIO USB2.0 cable from the MB

Figure 8 Disconnect FIO Type A cable from the MB

Figure 9 Disconnect FIO Type C cable from the MB

Figure 10 Disconnect HDD SATA cable from the MB

Figure 11 Disconnect PSU P2 cable from the MB

Figure 12 Disconnect ODD power cable from ODD

PSG instructions for this template are available at EL-MF877-01
Figure 13 Disconnect SATA cable from ODD

Figure 14 Remove the Memory card from the board

Figure 15 Press the ODD's latch on ODD cage

Figure 16 Remove the ODD from ODD cage

Figure 17 Disconnect SATA power cable from the MB

Figure 18 Disconnect MB PSU cable from the MB

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
Figure 19 Disconnect FIO LEDs/Switch cable from the MB
Figure 20 Disconnect Speaker cable from the MB

Figure 21 Disconnect FIO audio cable from the MB
Figure 22 Disconnect CPU Power cable from the MB

Figure 23 Disconnect ODD SATA cable from the MB
Figure 24 Disconnect system fan cable from the MB
Figure 25 Use PH1 screwdriver to remove system fan from chassis

Figure 26 Disconnect heatsink fan cable from MB

Figure 27 Use T-15 screwdriver to loose the screws and remove heatsink

Figure 28 Use PH1 screwdriver to loose the screws and remove the fan

Figure 29 Separate the fan from CPU heat sink

Figure 30 Rotate the handle and open it up

PSG instructions for this template are available at EL-MF877-01
Figure 31 Remove the CPU from the board
Figure 32 Remove the battery from the system board
Figure 33 Use T-15 screwdriver to lose the screws of MB from board
Figure 34 Remove MB from chassis
Figure 35 Remove front panel from chassis
Figure 36 Use T-15 screwdriver loose the screws of FIO
Figure 37 Remove FIO

Figure 38 Use T-15 screwdriver loose the screws of speaker and remove it

Figure 39 Remove the HDD from HDD cage

Figure 40 Use T-15 screwdriver remove the screws on the PSU chassis

Figure 41 Press the PSU’s latch on chassis

Figure 42 Remove the Power supply from chassis

PSG instructions for this template are available at EL-MF877-01
Figure 43 Use Micro shear 170II to cut the cable tie

Figure 44 Use PH1 screwdriver to remove screw for bottom

Figure 45 Use PH1 screwdriver to remove screw for top

Figure 46 Remove cover

Figure 47 Use PH1 screwdriver to remove FG screw

Figure 48 Use Micro shear 170II to cut the cable tie of fan

PSG instructions for this template are available at EL-MF877-01
Figure 49 Disconnect fan connector and inlet connector

Figure 50 Use PH1 screwdriver to remove PCB1 screw

Figure 51 Use PH1 screwdriver to remove AC inlet & Fan screw

Figure 52 Heat the solder of Electrolytic Capacitors greater than 2.5cm in diameter or height and remove it

PSG instructions for this template are available at EL-MF877-01